Preferred Device

# **Switching Transistor**

### **NPN Silicon**

#### **Features**

• Pb-Free Packages are Available

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	40	Vdc
Collector - Base Voltage	$V_{CBO}$	60	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	600	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

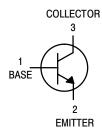
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in. 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.



#### ON Semiconductor®

#### http://onsemi.com





SOT-23 (TO-236) **CASE 318** STYLE 6

#### **MARKING DIAGRAM**



2X = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MMBT4401LT1	SOT-23	3000 Tape & Reel
MMBT4401LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT4401LT3	SOT-23	10,000 Tape & Reel
MMBT4401LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Cha	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS		•	•	•	•	
Collector - Emitter Breakdown Voltag	e (Note 3) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	40	_	Vdc	
Collector - Base Breakdown Voltage	$(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V <sub>(BR)CBO</sub>	60	_	Vdc	
Emitter - Base Breakdown Voltage	$(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	6.0	_	Vdc	
Base Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>BEV</sub>	-	0.1	μAdc	
Collector Cutoff Current	(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>CEX</sub>	-	0.1	μAdc	
ON CHARACTERISTICS (Note 3)		•	•			
DC Current Gain	$ \begin{array}{l} (I_{C}=0.1 \text{ mAdc},  V_{CE}=1.0  \text{Vdc}) \\ (I_{C}=1.0  \text{mAdc},  V_{CE}=1.0  \text{Vdc}) \\ (I_{C}=10  \text{mAdc},  V_{CE}=1.0  \text{Vdc}) \\ (I_{C}=150  \text{mAdc},  V_{CE}=1.0  \text{Vdc}) \\ (I_{C}=500  \text{mAdc},  V_{CE}=2.0  \text{Vdc}) \end{array} $	h <sub>FE</sub>	20 40 80 100 40	- - - 300 -	-	
Collector – Emitter Saturation Voltage	V <sub>CE(sat)</sub>	- -	0.4 0.75	Vdc		
Base - Emitter Saturation Voltage	V <sub>BE(sat)</sub>	0.75 -	0.95 1.2	Vdc		
SMALL-SIGNAL CHARACTERISTI	cs					
Current - Gain - Bandwidth Product	$(I_C = 20 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 100 \text{ MHz})$	f <sub>T</sub>	250	_	MHz	
Collector-Base Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>cb</sub>	-	6.5	pF	
Emitter-Base Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C <sub>eb</sub>	-	30	pF	
Input Impedance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>ie</sub>	1.0	15	kΩ	
Voltage Feedback Ratio	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>	
Small – Signal Current Gain	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>fe</sub>	40	500	-	
Output Admittance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>oe</sub>	1.0	30	μmhos	
SWITCHING CHARACTERISTICS						
Delay Time	(V <sub>CC</sub> = 30 Vdc, V <sub>EB</sub> = 2.0 Vdc,	t <sub>d</sub>	-	15	200	
Rise Time	I <sub>C</sub> = 150 mAdc, I <sub>B1</sub> = 15 mAdc)	t <sub>r</sub>	-	20	ns	
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	t <sub>s</sub>	_	225	200	
Fall Time $I_{B1} = I_{B2} = 15 \text{ mAdc})$		t <sub>f</sub>	-	30	ns	

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### **SWITCHING TIME EQUIVALENT TEST CIRCUITS**

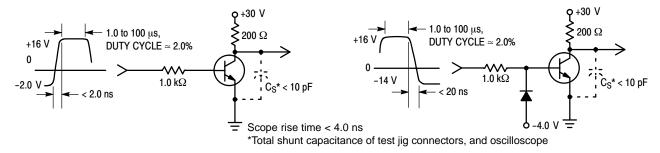
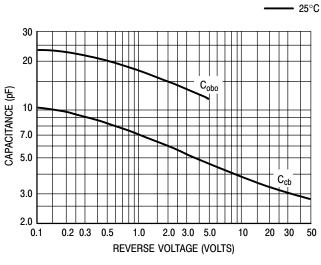


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

#### TRANSIENT CHARACTERISTICS

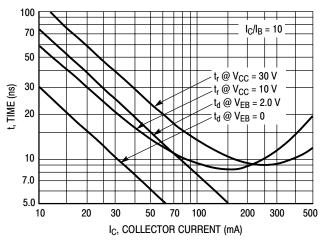
—— 100°C



10 7.0  $V_{CC}$  = 30 V5.0  $I_C/I_B = 10$ 3.0 2.0 Q, CHARGE (nC) 1.0 0.7 0.5 0.3 0.2 0.1 20 10 70 100 200 300 50 500 IC, COLLECTOR CURRENT (mA)

Figure 3. Capacitances

Figure 4. Charge Data



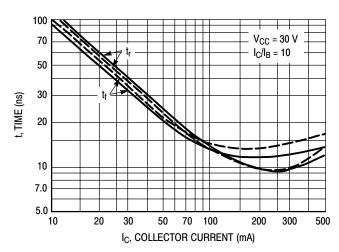
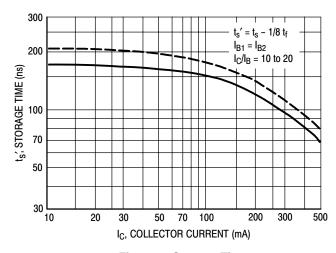


Figure 5. Turn-On Time

Figure 6. Rise and Fall Times



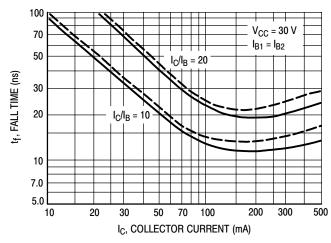


Figure 7. Storage Time

Figure 8. Fall Time

#### SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = 10 \text{ Vdc}, T_A = 25^{\circ}\text{C}; Bandwidth = 1.0 \text{ Hz}$ 

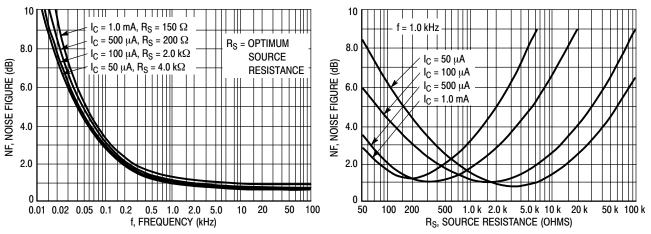


Figure 9. Frequency Effects

Figure 10. Source Resistance Effects

#### h PARAMETERS

 $V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C}$ 

This group of graphs illustrates the relationship between  $h_{fe}$  and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4401LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

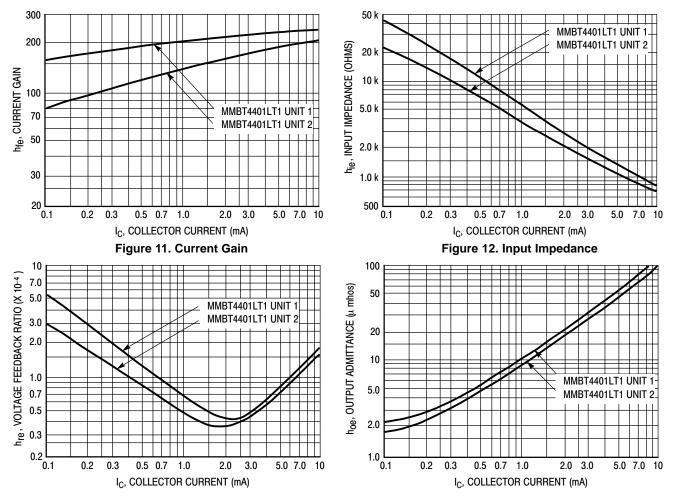


Figure 13. Voltage Feedback Ratio

Figure 14. Output Admittance

#### STATIC CHARACTERISTICS

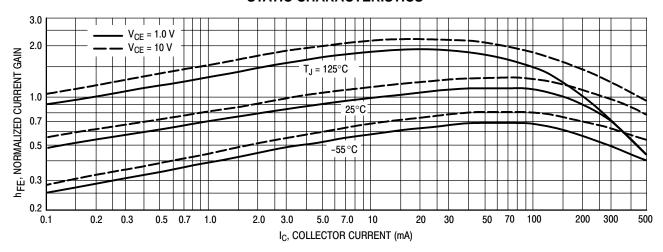


Figure 15. DC Current Gain

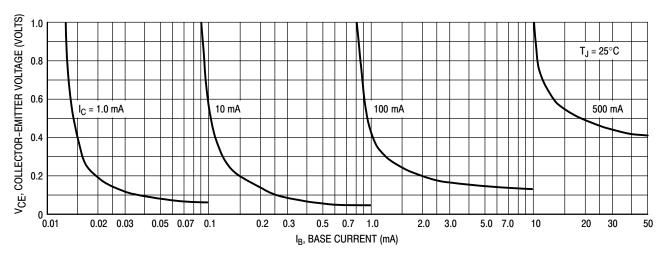


Figure 16. Collector Saturation Region

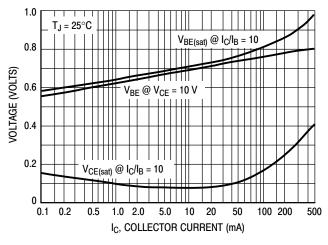
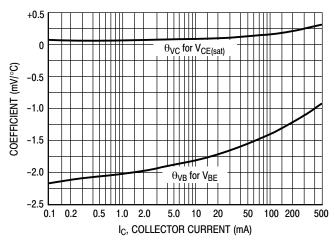


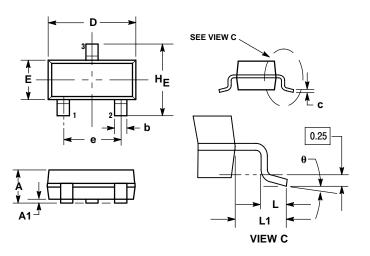
Figure 17. "On" Voltages



**Figure 18. Temperature Coefficients** 

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER

  - ANSI Y14.5M, 1982.

    2. CONTROLLING DIMENSION: INCH.

    3. MAXIMUM LEAD THICKNESS INCLUDES
    LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  - 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

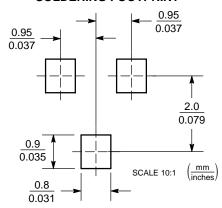
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

PIN 1. BASE **EMITTER** 2.

COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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